SysInt 2022
System-Integrated Intelligence

7-9 September Genova - Italy

6th International Conference on System-Integrated Intelligence

Intelligent, flexible and connected systems in products and production

CALL FOR PAPERS

ABOUT SYSINT

SysInt is an international conference about system-integrated intelligence, held biannually. The conference provides a forum for academia and industry to disseminate their latest innovations and practices in field of system-integrated intelligence.

The goal is to present recent and exciting results on the integration of new, intelligent functionalities into materials, components, systems and products.

The conference addresses industry and society needs, requirements and expectations.

Remote participation will be possible

SCIENTIFIC TRACKS

The **6th edition** will take place in **Genova, Italy**. The conference will be organized into the following Scientific Tracks:

- Artificial Intelligence
- Pervasive and Ubiquitous Intelligence
- Sensors and Sensing Systems
- Smart Factory and Logistic Systems
- Structural Health Monitoring
- Soft Robotics
- Human Machine Interaction
- Cognitive Systems

Suggestions for further special sessions are encouraged.

IMPORTANT DATES

SPECIAL SESSION DEADLINE:
March 1st, 2022
NOTIFICATION SPECIAL SESSIONS:
March 7th, 2022
REGULAR PAPERS DEADLINE:
April 1st, 2022
TUTORIAL DEADLINE:
May 13th ,2022
NOTIFICATION REGULAR PAPERS:
June 1st, 2022
NOTIFICATION TUTORIALS:
May 31th, 2022
CAMERA READY DEADLINE:
July 1st, 2022

SUBMIT YOUR WORK

The technical committee invites authors to submit maximum 5-page papers in standard double-column format, including figures and tables, to clearly present the work, methods, originality, significance and applications of the techniques discussed. The last page should be dedicated to references.
All accepted papers will be published in proceedings with ISBN and DOI.

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COSMIC lab CONNECTED OBJECTS SENSING MATERIALS INTEGRATED CIRCUITS

IEEE Sensors Council ITALY CHAPTER

IRP

ASME ITALY SECTION